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Mesoscale Modeling of Colloidal Films Dried with Controlling the Morphology of Aggregated Particles

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Material Fabrication from Colloidal Suspensions²



Electrical/Thermal conductivity

Optical property

- Porosity
- Contact network

Structure Formation during Drying



Objective

- Modeling of adhesion to describe the various morphologies of aggregated particles
- Effects of adhesion on structure formation during drying







Diffusion-limited

Reaction-limited

Adhesion: Fixation of contact points (Reaction)

Equations of Particles' Motion

$$M\dot{V} = -\xi V + F^{R} + F^{cnt} + F^{DLVO} + F^{cpl}$$
$$I\dot{\Omega} = -\zeta \Omega + N^{R} + N^{cnt}$$



Hydrodynamic force/torque

Drag + Fluctuations \rightarrow Brownian motion



DLVO force





Capillary force



Vertical push into liquid

TIT TIT

Lateral attraction

Modeling of Adhesion

$$M\dot{V} = -\xi V + F^{R} + F^{cnt} + F^{DLVO} + F^{cpl}$$
$$I\dot{\Omega} = -\zeta \Omega + N^{R} + N^{cnt}$$



How does adhesion affect the structure of particles?



Drying Curve of Colloidal Suspensions



Drying time

Drying rate vs. Structure

Modeling of Falling Drying Rate



Drying Curves



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Strength of Structure



Drying of colloidal droplets

Compression

Porosity vs. Strength



Particle diameter: d = 20 nm, Zeta potential: -50 mV





-3

 F_{w2}

 $\rightarrow x$

Structure





	Diameter	Porosity	Strength
Slip	10.2	0.07	0.35
Stick	11.5	0.34	0.64

Strong granule with high porosity

Network Formation of Particles



Aqueous suspensions of nanoparticles

Example of network structure: Wakabayashi et al., Langmuir (2007).

Transparent conductive films

How do network structures form?

200 nm



Particle diameter: d = 10 nm



Summary

- Modeling of adhesion between particles
 → Morphologies of aggregate
 - Constraint on relative motions between contacting particles
 → Fixation of contact points
 - Possible factor of adhesion in real systems: Binder addition
- Adhesion → Structures with high porosity formed during drying
 - High permeability (drying rate)
 - High strength
 - Network structures \rightarrow Transparent conductive films